



## Material Content Data Sheet



<b>Sales Product Name</b>	TLE6240GP			<b>Issued</b>	26. September 2017			
<b>MA#</b>	MA000693880							
<b>Package</b>	PG-DSO-36-48			<b>Weight*</b>	2110.27 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	26.849	1.27	1.27	12723	12723
leadframe	inorganic material	phosphorus	7723-14-0	0.388	0.02		184	
	non noble metal	zinc	7440-66-6	1.553	0.07		736	
	non noble metal	iron	7439-89-6	31.066	1.47		14721	
wire	non noble metal	copper	7440-50-8	1261.410	59.79	61.35	597748	613389
	non noble metal	copper	7440-50-8	3.138	0.15	0.15	1487	1487
	encapsulation	organic material	carbon black	1333-86-4	1.507	0.07		714
plastics		epoxy resin	-	69.318	3.28		32848	
	inorganic material	silicondioxide	60676-86-0	682.632	32.35	35.70	323481	357043
leadfinish	non noble metal	tin	7440-31-5	15.044	0.71	0.71	7129	7129
plating	noble metal	silver	7440-22-4	0.644	0.03	0.03	305	305
solder	non noble metal	tin	7440-31-5	0.167	0.01		79	
	noble metal	silver	7440-22-4	0.251	0.01		119	
	non noble metal	lead	7439-92-1	16.303	0.77	0.79	7726	7924
*deviation	< 10%			Sum in total:		100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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